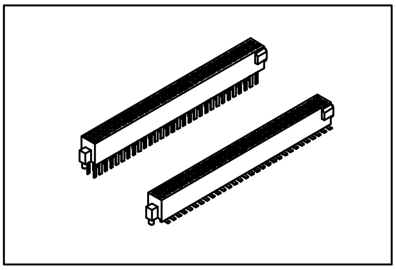
P.C.B. Socket 1.27mmX1.27mm(0.050"X0.050") GXCON



Features:

- * Choice of through-hole and surface mount.
- * Low profile 4.57mm(0.180").
- * Choice of alignment post or Board lock options.
- * Choice of two different dip length.

Material:

Housing: High temperature housing withstands IR and VPR soldering methods.

Contacts: Phosphor Bronze.

Plating: Gold plated over nickel.
Tin plated over nickel.
Selective gold plated: Gold plated on mating area and tin plated on solder tail.

Electrical Characteristics:

Current Rating: 1 AMP.

Insulator Resistance: 5000MΩmin. at DC 500V.

Contact Resistance: 20mΩmax. at DC 100mA.

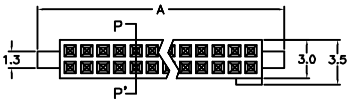
Operating Temperature: -65°C~+125°C.

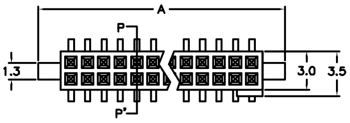
Max Processing Temperature: 230°Cfor 30~60 seconds.

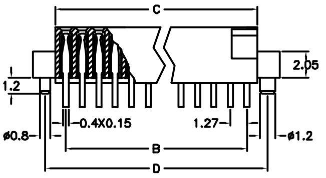
Mechanical Characteristics:

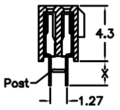
Insertion Force: 140g avg.(0.46mm dia. pin)

Withdrawal Force: 114g avg.(0.46mm dia. pin)

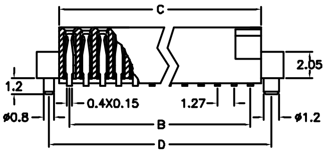


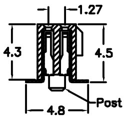




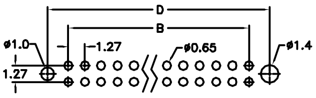


Section P-P'
Dip Type

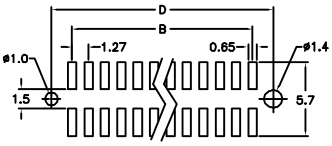




Section P-P'
S.M.D Type



P.C. Board Layout



P.C. Board Layout

X	1	2	3
Length	3.05	1.91	2.30
Position Dimension	10 Thru 100		
A	1.27 X No. of Positions /2+3.78		
B	1.27 X No. of Positions /2−1.27		
C	1.27 X No. of Positions /2+0.38		
D	1.27 X No. of Positions /2+1.91		

Ordering information

PS23-	100	1	1	P	1
Series	No. of Position	3: Selective Gold Plated 1: Gold Plated	1: Straight 3: Surface Mount	P: With Post N: Without Post L: With Board Lock	*1: 3.05mm *2: 1.91mm *3: 2.30mm